



深圳市信德意电子有限公司

常备现货 快速取样 购买请联系朱小姐  
手机: 13510666820 QQ: 2355608068  
网址: www.cxtke.com



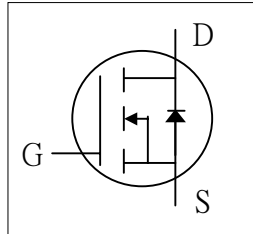
**Advanced Power  
Electronics Corp.**

**AP9T18GH/J**

**RoHS-compliant Product**

*N-CHANNEL ENHANCEMENT MODE  
POWER MOSFET*

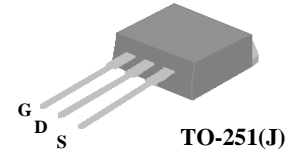
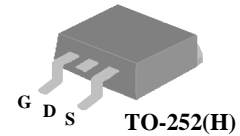
- ▼ Low Gate Charge
- ▼ Capable of 2.5V gate drive
- ▼ Surface mount package



$BV_{DSS}$	20V
$R_{DS(ON)}$	14m $\Omega$
$I_D$	38A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, ultra low on-resistance and cost-effectiveness.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 16$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS}$ @ 4.5V	38	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS}$ @ 4.5V	24	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	140	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	31.3	W
	Linear Derating Factor	0.25	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	4	$^\circ C/W$
Rthj-a	Maximum Thermal Resistance, Junction-ambient	110	$^\circ C/W$



## AP9T18GH/J

### Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}, I_D=1\text{mA}$	-	0.1	-	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=4.5V, I_D=18A$	-	-	14	$m\Omega$
		$V_{GS}=2.5V, I_D=9A$	-	-	28	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	-	1.5	V
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=18A$	-	33	-	S
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V$	-	-	1	$\mu A$
	Drain-Source Leakage Current ( $T_j=150^\circ\text{C}$ )	$V_{DS}=16V, V_{GS}=0V$	-	-	25	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=\pm 16V$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_D=18A$	-	16	25	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=16V$	-	3	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	9	-	nC
$t_{d(on)}$	Turn-on Delay Time <sup>2</sup>	$V_{DS}=10V$	-	12	-	ns
$t_r$	Rise Time	$I_D=18A$	-	80	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega, V_{GS}=5V$	-	22	-	ns
$t_f$	Fall Time	$R_D=0.56\Omega$	-	12	-	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	1115	1790	pF
$C_{oss}$	Output Capacitance	$V_{DS}=20V$	-	280	-	pF
$C_{rss}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	220	-	pF
$R_g$	Gate Resistance	$f=1.0\text{MHz}$	-	1.54	-	$\Omega$

### Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=18A, V_{GS}=0V$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$I_S=18A, V_{GS}=0V,$	-	19	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI/dt=100A/\mu s$	-	11	-	nC

#### Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

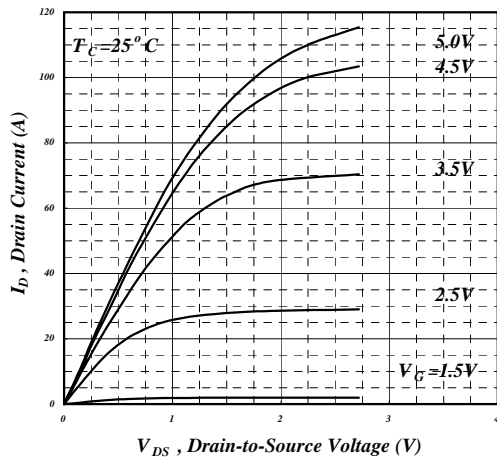


Fig 1. Typical Output Characteristics

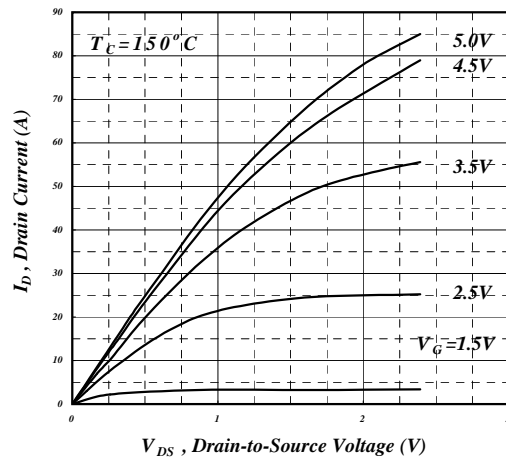


Fig 2. Typical Output Characteristics

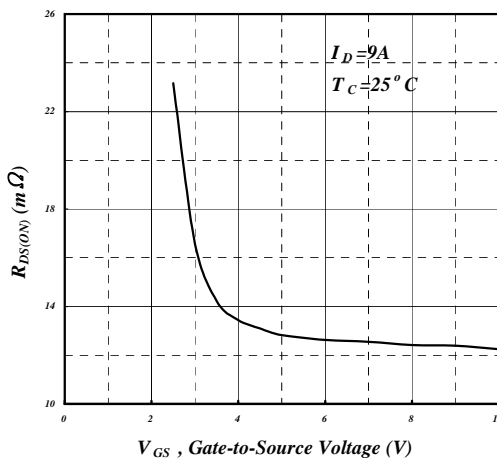


Fig 3. On-Resistance v.s. Gate Voltage

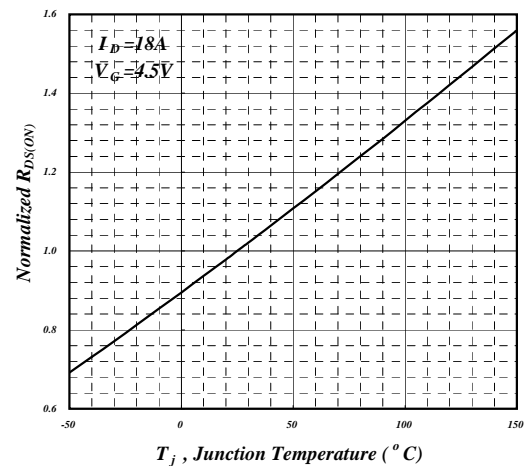


Fig 4. Normalized On-Resistance v.s. Junction Temperature

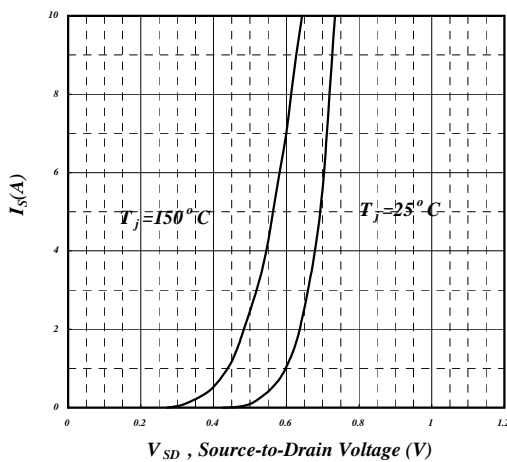


Fig 5. Forward Characteristic of Reverse Diode

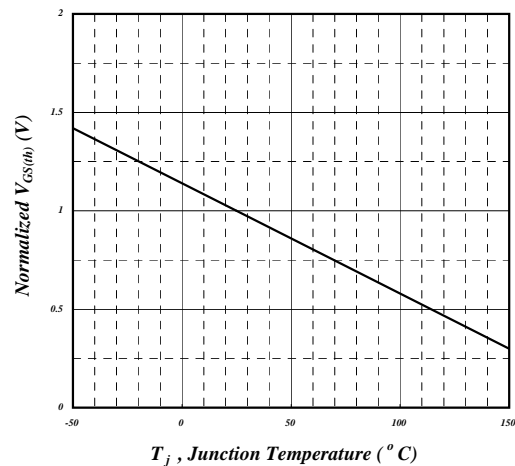


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



# AP9T18GH/J

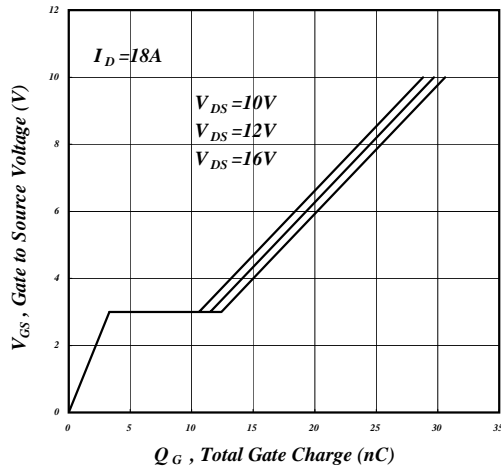


Fig 7. Gate Charge Characteristics

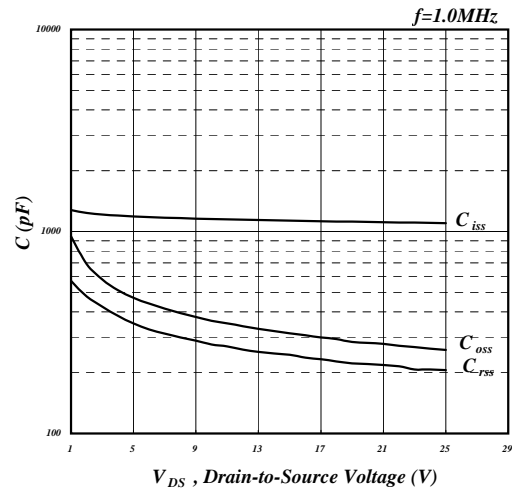


Fig 8. Typical Capacitance Characteristics

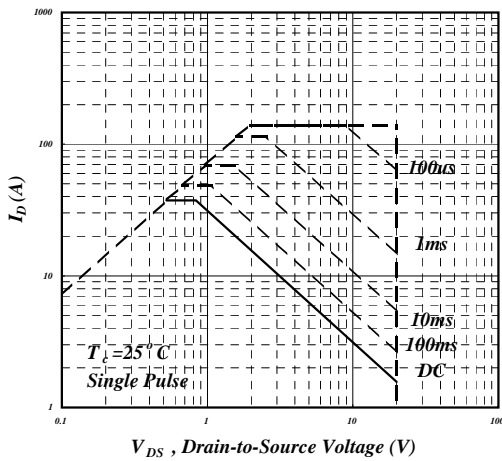


Fig 9. Maximum Safe Operating Area

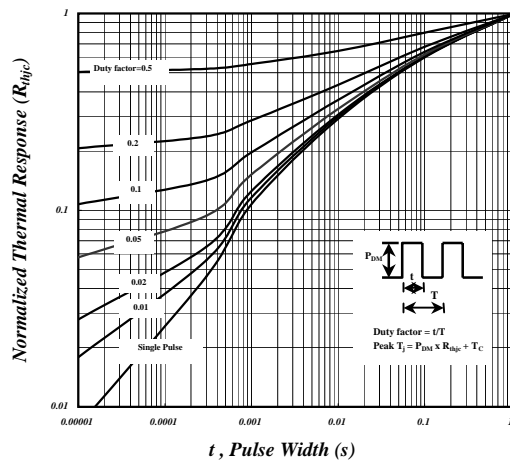


Fig 10. Effective Transient Thermal Impedance

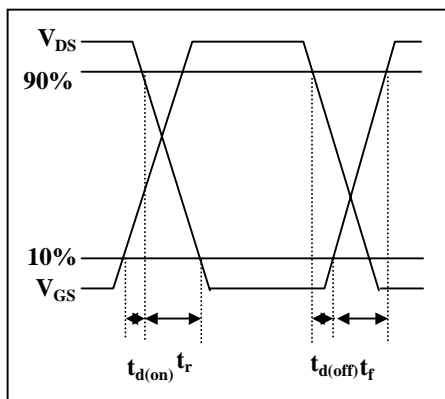


Fig 11. Switching Time Waveform

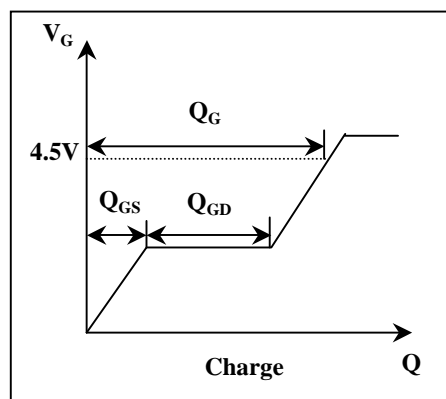
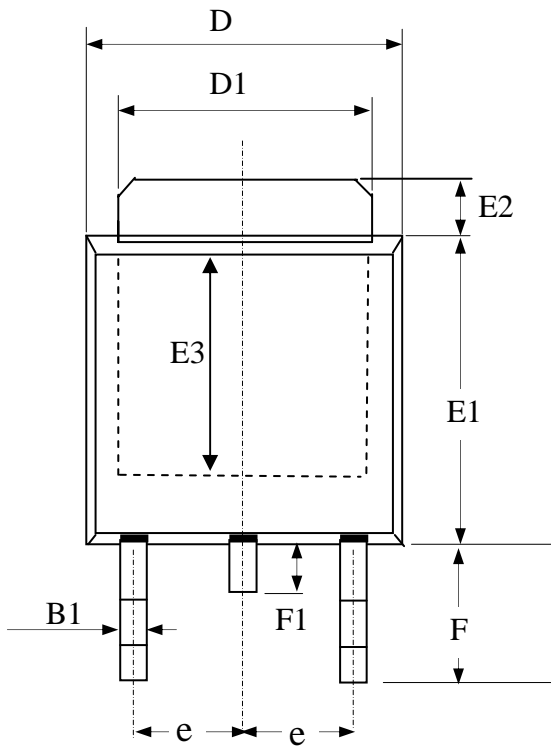


Fig 12. Gate Charge Waveform



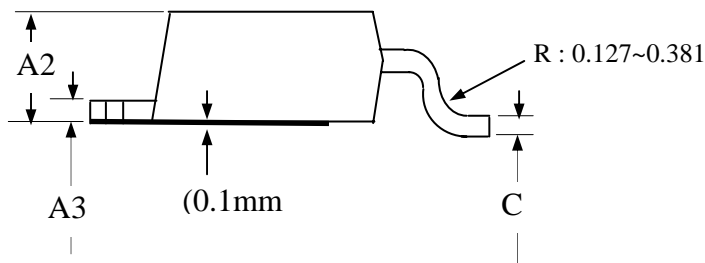
### Package Outline : TO-252



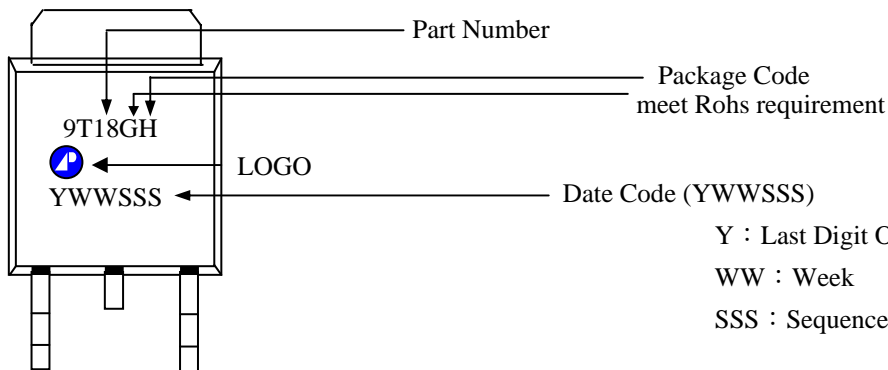
SYMBOLS	Millimeters		
	MIN	NOM	MAX
A2	1.80	2.30	2.80
A3	0.40	0.50	0.60
B1	0.40	0.70	1.00
D	6.00	6.50	7.00
D1	4.80	5.35	5.90
E3	3.50	4.00	4.50
F	2.20	2.63	3.05
F1	0.5	0.85	1.20
E1	5.10	5.70	6.30
E2	0.50	1.10	1.80
e	--	2.30	--
C	0.35	0.50	0.65

1.All Dimensions Are in Millimeters.

2.Dimension Does Not Include Mold Protrusions.



### Part Marking Information & Packing : TO-252



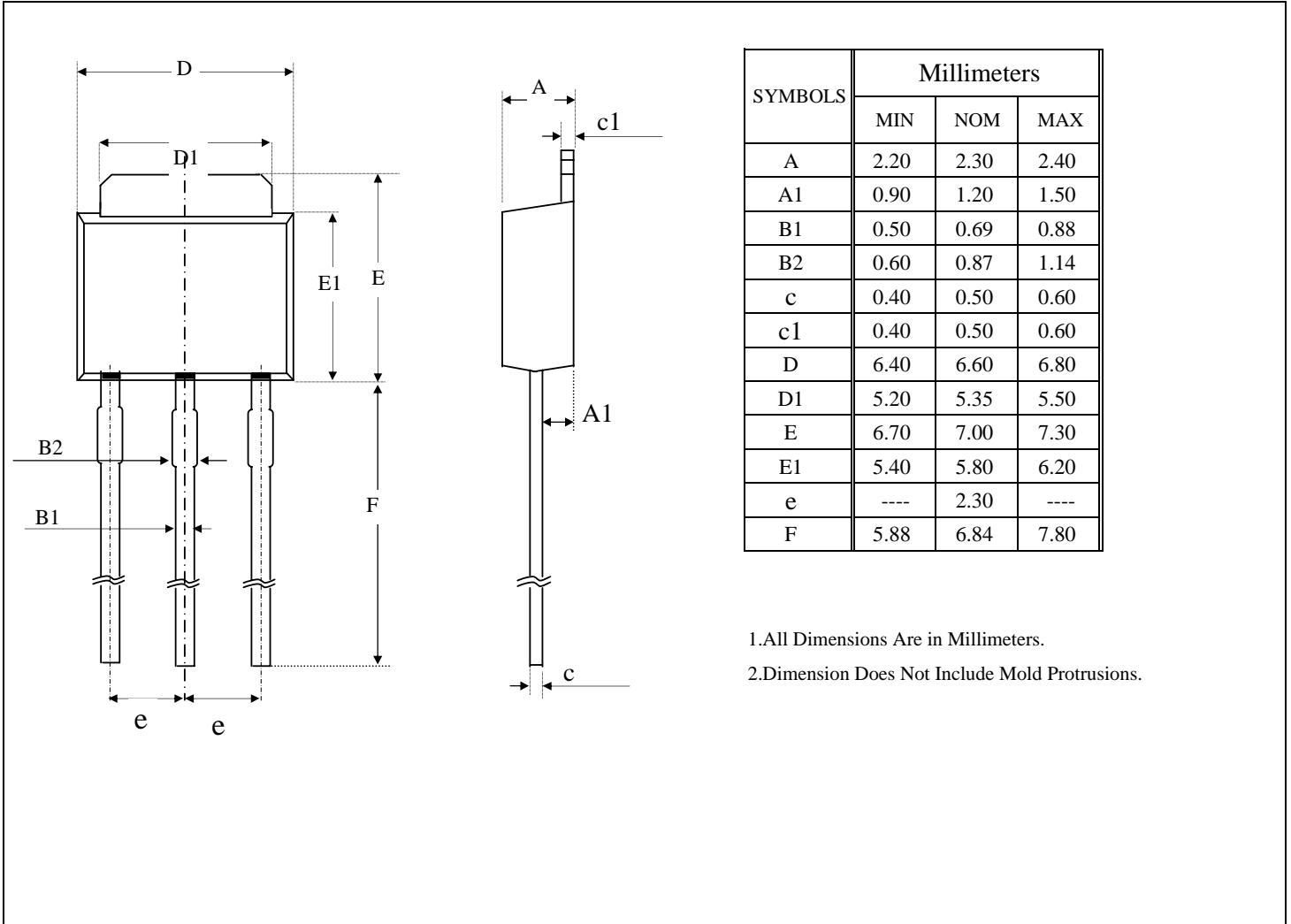
Y : Last Digit Of The Year

WW : Week

SSS : Sequence



### Package Outline : TO-251



### Part Marking Information & Packing : TO-251

